



Product Change Notification

Change Notification #: 117482 - 00
Change Title: Select Intel® Optane™ SSD 900P Series and Intel® Optane™ SSD 905P Series Products, PCN 117482-00, Documentation, Booklet Change
Date of Publication: March 19, 2020

Key Characteristics of the Change:

Documentation



Forecasted Key Milestones:







Date Customer Must be Ready to Receive Post-Conversion Material:	April 4, 2020
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Description of Change to the Customer:

The Intel® Optane™ SSD 900P Series and Intel® Optane™ SSD 905P Series SKUs listed in the products affected table below will have the booklet changed to update the EU single point of contact.

See pictures for example of before and after.

Existing booklet J42547-002 (only page 2 and the IPN on the last page change)	New booklet changes J42547-003
Cover Page  Intel® Solid State Drive • AIC and U.2 Form Factor Installation Instructions • Five Year Limited Warranty	Cover Page (no change)  Intel® Solid State Drive • AIC and U.2 Form Factor Installation Instructions • Five Year Limited Warranty

<p>Page 2</p> <p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1549 USA</p> <p>EU Single Point of Contact: Intel Corporation (UK) Ltd. Attn: Corp. Quality Pipers Way, Swindon, Wiltshire SN3 1RJ UK</p>  <p>In the EU, this symbol means that this product must not be disposed of with household waste. It is your responsibility to bring it to a designated collection point for the recycling of waste electrical and electronic equipment. For more information, please contact your local waste collection center or your point of purchase.</p> <p>Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709A requirements, and the PCB/Substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.</p> <p>Intel and the Intel logo are trademarks of Intel Corporation in the U.S. and/or other countries.</p> <p>*Other names and brands may be claimed as the property of others.</p> <p>© 2018 Intel Corporation</p>	<p>Page 2 (EU single point of Contact information change)</p> <p>Intel Corporation 2200 Mission College Blvd Santa Clara, CA 95054-1549 USA</p> <p>EU Single Point of Contact: Intel Deutschland GmbH Attn: Corp. Quality Am Campeon 10-12, 85579 Neubiberg, Germany</p>  <p>In the EU, this symbol means that this product must not be disposed of with household waste. It is your responsibility to bring it to a designated collection point for the recycling of waste electrical and electronic equipment. For more information, please contact your local waste collection center or your point of purchase.</p> <p>Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709A requirements, and the PCB/Substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.</p> <p>Intel and the Intel logo are trademarks of Intel Corporation in the U.S. and/or other countries.</p> <p>*Other names and brands may be claimed as the property of others.</p> <p>© 2019 Intel Corporation</p>
<p>Back page</p>  <p>J42547-002</p> 	<p>Back page (new IPN/barcode)</p>  <p>J42547-003</p> 

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, function, quality or reliability of the product. This change affects the warranty booklet inside the packaging.

Customers should be aware of the change and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#	TA
Intel® Optane™ SSD 900P Series (280GB, 1/2 Height PCIe x4, 3D XPoint™) Reseller Single Pack	SSDPED1D280GAX1	945760	H93319-304
Intel® Optane™ SSD 900P Series (480GB, 1/2 Height PCIe x4, 3D XPoint™) Reseller Single Pack	SSDPED1D480GAX1	945761	H93320-304
Intel® Optane™ SSD 905P Series (960GB, 1/2 Height PCIe x4, 3D XPoint™) Reseller Single Pack	SSDPED1D960GAX1	945762	J60240-303
Intel® Optane™ SSD 905P Series (1.5TB, 1/2 Height PCIe x4, 3D XPoint™) Reseller Single Pack	SSDPED1D015TAX1	945763	J60241-302
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint™) Reseller Single Pack	SSDPE21D280GAX1	956949	J60242-102
Intel® Optane™ SSD 905P Series (480GB, 2.5in PCIe x4, 3D XPoint™) Reseller Single Pack with Standard U.2 Cable	SSDPE21D480GAX1	956950	J60243-102
Intel® Optane™ SSD 905P Series (960GB, 2.5in PCIe x4, 3D XPoint™) Reseller Single Pack with Standard U.2 Cable	SSDPE21D960GAX1	956955	J60244-101
Intel® Optane™ SSD 905P Series (1.5TB, 2.5in PCIe x4, 3D XPoint™) Reseller Single Pack with Standard U.2 Cable	SSDPE21D015TAX1	956956	J60245-101
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint™)	SSDPE21D280GAM3	959525	J65427-102
Intel® Optane™ SSD 905P Series (480GB, 2.5in PCIe x4, 3D XPoint™) Reseller Single Pack with M.2 Adapter Cable	SSDPE21D480GAM3	959526	J65428-102
Intel® Optane™ SSD 905P Series (960GB, 2.5in PCIe x4, 3D XPoint™) Reseller Single Pack with M.2 Adapter Cable	SSDPE21D960GAM3	959527	J65429-101
Intel® Optane™ SSD 905P Series (1.5TB, 2.5in PCIe X4, 3D XPoint™) Reseller Single Pack with M.2 Adapter Cable	SSDPE21D015TAM3	959528	J65430-101
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint™)	SSDPE21D280GASM	962750	J78487-102
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint™)	SSDPE21D280GASX	962751	J78488-102
Intel® Optane™ SSD 900P Series (280GB, ½ Height PCIe 3.0 X4, 20nm 3D XPoint™)	SSDPED1D280GASX	962752	J78489-304
Intel® Optane™ SSD 900P Series (480GB, ½ Height PCIe 3.0 X4, 20nm 3D XPoint™)	SSDPED1D480GASX	962754	J78490-304

PCN Revision History:

Date of Revision:

March 19, 2020

Revision Number:

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Reason:

Originally Published PCN



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117482 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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